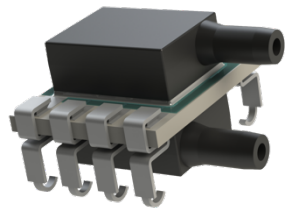


# MATERIAL DECLARATION SHEET



Material Number	BPS125 Digital Low-Pressure Sensor			
Product Line	Sensors			
Compliance Date	November 8 <sup>th</sup> , 2019			
RoHS Compliant	Yes	MSL	N/A	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic substrate B	Alumina	0.881	Aluminum oxide	1344-28-1	96.3	64.9023	67.396
				Dimethyl phthalate	131-11-3	0.245	0.1651	
				Manganese oxide	1313-13-9	0.03	0.0202	
				Lead	7439-92-1	0.0075	0.0051	
				Silver	7440-22-4	2.3875	1.6091	
				Platinum	7440-06-4	0.03	0.0202	
				Gold	7440-57-5	1	0.6740	
2	MEMS Die B	Glass	0.0208	Borosilicate	65997-17-3	69.95	1.1129	1.591
				Silicon	7440-21-3	29.98	0.4770	
				Aluminum	7429-90-5	0.07	0.0011	
3	Capacitor	Capacitor	0.002	Ceramic materials	66402-68-4	96.77	0.1480	0.153
				Tin	7440-31-5	1.62	0.0025	
				Nickel	7440-02-0	1.61	0.0025	
4	Solder	Solder	0.0005	Tin	7440-31-5	96.15	0.0367	0.038
				Silver	7440-22-4	3.31	0.0013	
				Copper	7440-50-8	0.54	0.0002	

# MATERIAL DECLARATION



5	Plastic cover	PPS	0.3	Poly(1,4-phenylene sulfide)	26125-40-6	60	13.77	22.950
				Glass fiber	65997-17-3	40	9.18	
6	Pin	Copper alloy	0.1	Copper	7440-50-8	94	7.191	7.650
				Tin	7440-31-5	6	0.459	
7	ASIC Die 1	Die	0.0029	Silicon	7440-21-3	97.78	0.2171	0.222
				Aluminum	7429-90-5	0.12	0.0003	
				Polyimide	60842-76-4	1.42	0.0031	
				Silicon dioxide	7631-86-9	0.41	0.0009	
				Trisilicon-tetranitride	12033-89-5	0.23	0.0005	
				Titanium nitride	25583-20-4	0.03	0.0001	
		Total weight	1.3072					

**This Document was updated on:** 11-8-2019

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.